Semiconductor Device Type: **T3X-QFN-44-8x8x0.9mm-MatteTin**

Sub-Component	Basic Substance	CAS Number	% Total Weight	mg/part	ppm
Die	Silicon	7440-21-3	2.83	5.33	28292
Plating & Anode Ball	Other	Trade Secret	0.00	0.00	12
Plating & Anode Ball	Tin	7440-31-5	1.24	2.34	12409
Die Attach Epoxy	Silver	7440-22-4	1.25	2.35	12462
Die Attach Epoxy	1,6-Hexanediol diacrylate	13048-33-4	0.02	0.03	160
Die Attach Epoxy	N-Methyl-2-pyrrolidone	872-50-4	0.02	0.03	160
Die Attach Epoxy	Isobornyl methacrylate	7534-94-3	0.16	0.30	1598
Die Attach Epoxy	Lauryl acrylate	2156-97-0	0.16	0.30	1598
Bonding Wire	Gold	7440-57-5	0.24	0.45	2388
Mold Compound	Metal hydroxide	Trade Secret	1.10	2.07	10988
Mold Compound	Carbon Black	1333-86-4	0.22	0.41	2198
Mold Compound	Epoxy Resin	Trade Secret	3.08	5.80	30766
Mold Compound	Phenolic Resin	Trade Secret	2.20	4.14	21976
Mold Compound	Vitreous silica	60676-86-0	37.36	70.38	373587
Lead Frame	Copper	7440-50-8	47.94	90.32	479445
Lead Frame	Phosphorus	7723-14-0	0.02	0.03	150
Lead Frame	Zinc	7440-66-6	0.08	0.14	752
Lead Frame	Silver	7440-22-4	0.95	1.79	9527
Lead Frame	Iron	7439-89-6	1.15	2.17	11532
		TOTALS:	**100.00**	**188.39**	**1,000,000**

188.39 mg Total Mass

Package Homogeneous Materials

5.33	**(mg) Total**	**Die**	**% of Total Weight**	**2.83**
	Silicon	7440-21-3	100.00	
		Total	**100.00**	
2.34	**(mg) Total**	**Plating & Anode Ball**	**% of Total Weight**	**1.24**
	Other	Trade Secret	0.10	
	Tin	7440-31-5	99.90	
		Total	**100.00**	
3.01	**(mg) Total**	**Die Attach Epoxy**	**% of Total Weight**	**1.60**
	Silver	7440-22-4	78.00	
	1,6-Hexanediol diacrylate	13048-33-4	1.00	
	N-Methyl-2-pyrrolidone	872-50-4	1.00	
	Isobornyl methacrylate	7534-94-3	10.00	
	Lauryl acrylate	2156-97-0	10.00	
		Total	**100.00**	
0.45	**(mg) Total**	**Bonding Wire**	**% of Total Weight**	**0.24**
	Gold	7440-57-5	100.00	
		Total	**100.00**	
82.80	**(mg) Total**	**Mold Compound**	**% of Total Weight**	**43.95**
	Metal hydroxide	Trade Secret	2.50	
	Carbon Black	1333-86-4	0.50	
	Epoxy Resin	Trade Secret	7.00	
	Phenolic Resin	Trade Secret	5.00	
	Vitreous silica	60676-86-0	85.00	
		Total	**100.00**	
94.46	**(mg) Total**	**Lead Frame**	**% of Total Weight**	**50.14**
	Copper	7440-50-8	95.62	
	Phosphorus	7723-14-0	0.03	
	Zinc	7440-66-6	0.15	
	Silver	7440-22-4	1.90	
	Iron	7439-89-6	2.30	
188.39		**Total**	**100.00**	100.00

The information contained in this Material Content Declaration (MCD) consists of package-level information and is not part number specific. This information is considered to be sufficiently representative of all part numbers for the package type.

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